

Semiconductor Technologies for Energy Storage Integration

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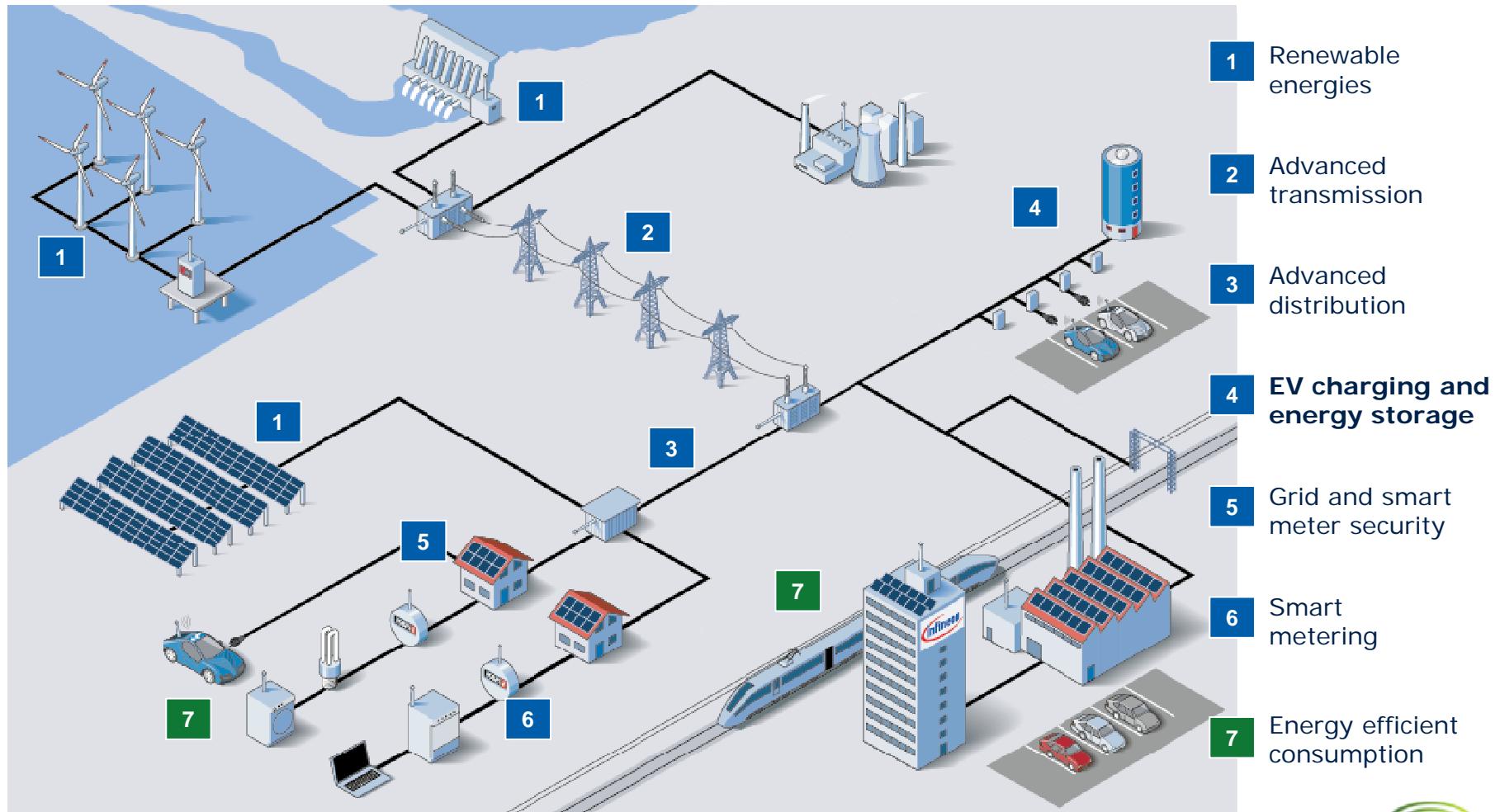


Infineon at a Glance

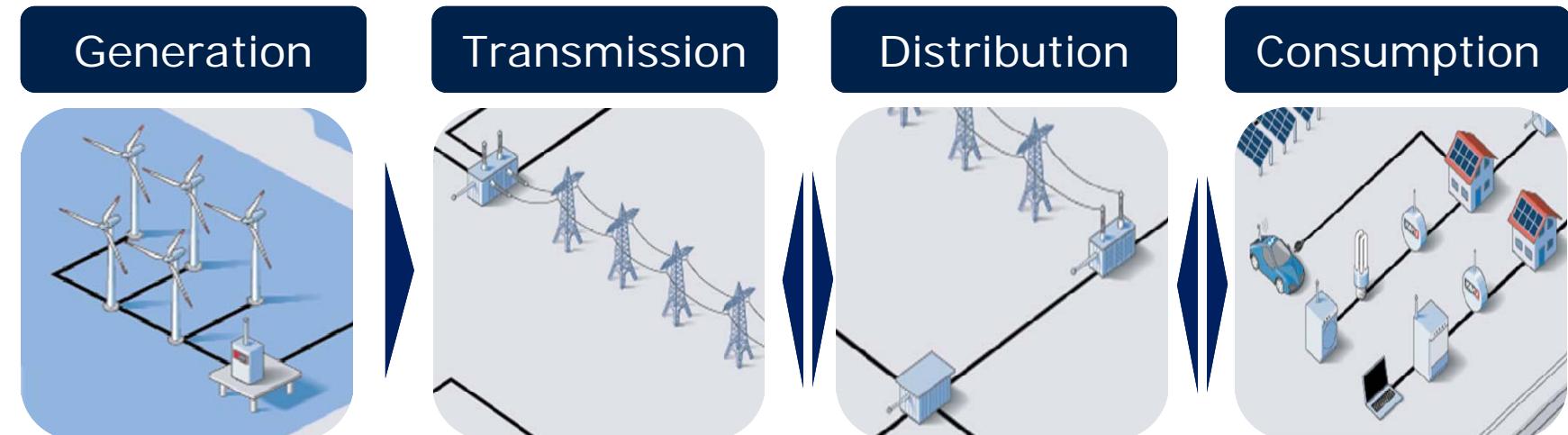
The Company

- Infineon provides semiconductor and system solutions, focusing on three central needs of our modern society:
Energy Efficiency, Mobility and Security
- Revenue in FY 2011: 3.997 billion EUR
- 26,454 employees worldwide (as of June 2012)
- 15,700 patents and patent applications (as of Sept. 2011)
- More than 20 R&D locations
- Germany's largest / Europe's second largest semiconductor company
- Market position: #2 Automotive - #1 Power - #1 Chip Card

Infineon's View of the Smart Grid



Semiconductor Applications and Products in the Smart Grid



Major Applications

- Renewable energy integration
- Flexible AC Transmission Systems (FACTS)
- High-Voltage DC Transmission Systems (HVDC)

Energy storage systems

- Advanced sensing
- Solid state switch gear
- Smart transformers
- Advanced metering infrastructure (AMI)
- Micro grids

Electric vehicle charging

- Energy storage
- Distributed generation
- Smart meters
- Smart thermostats
- Smart appliances
- LED lighting

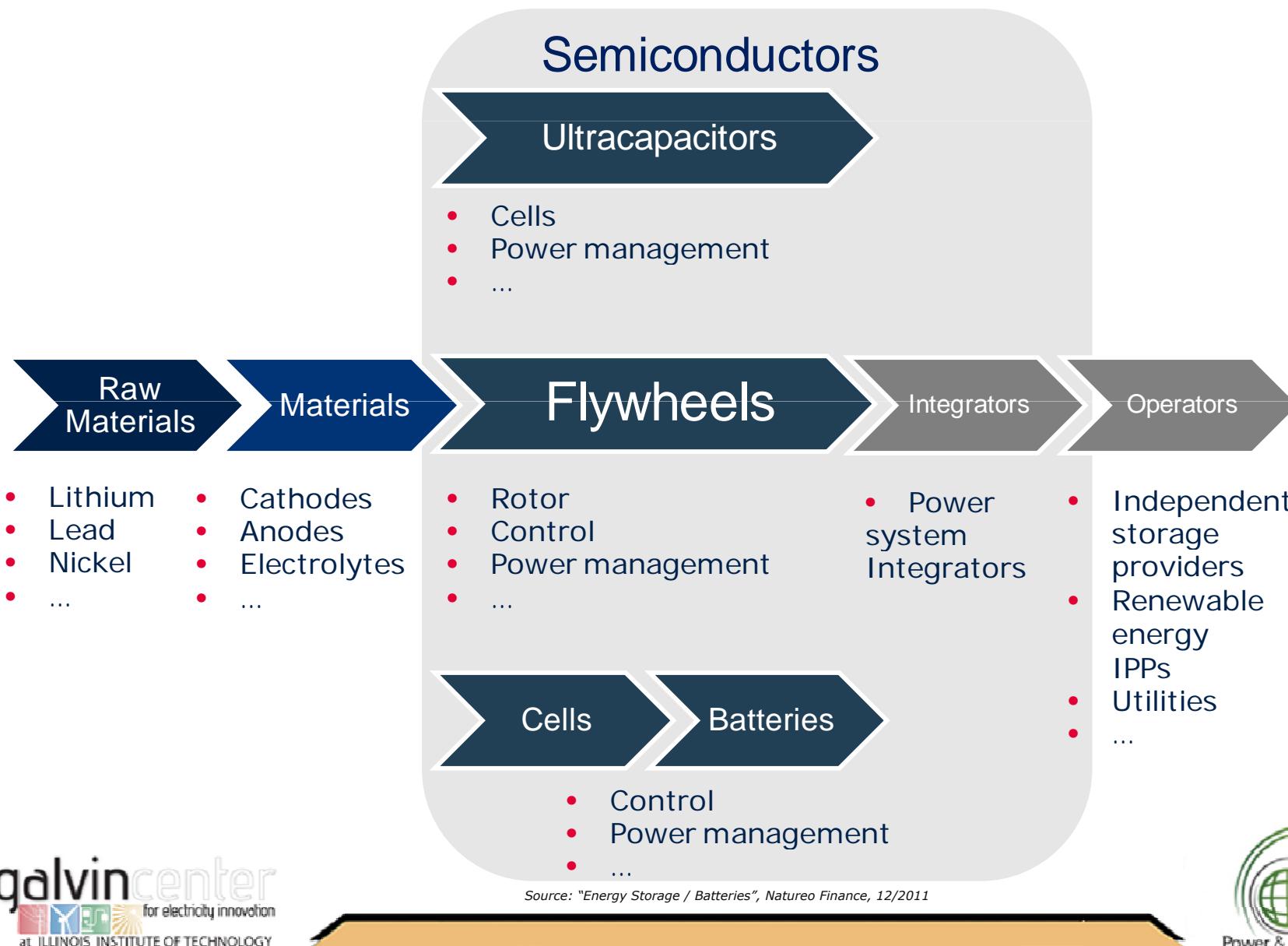
Major Products

- Power semiconductors
- Drivers & controllers
- Power semiconductors
- Drivers & controllers

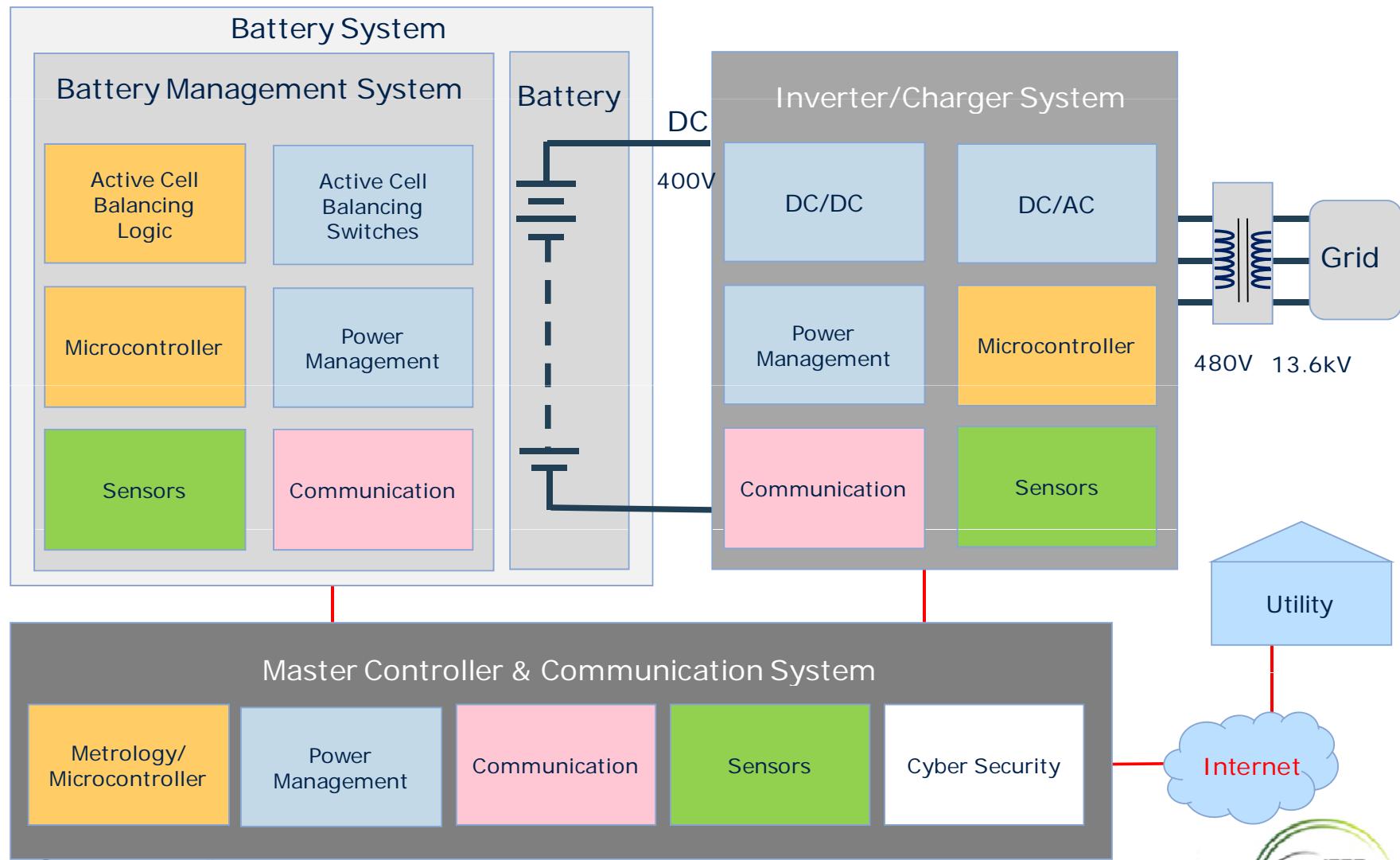
- Power semiconductors
- Drivers & controllers
- Sensors
- Security ICs
- Communication ICs

- Power semiconductors
- Drivers & controllers
- Smart meter ICs
- Sensors
- Security ICs
- Communication ICs

Semiconductors in the Energy Storage Value Chain

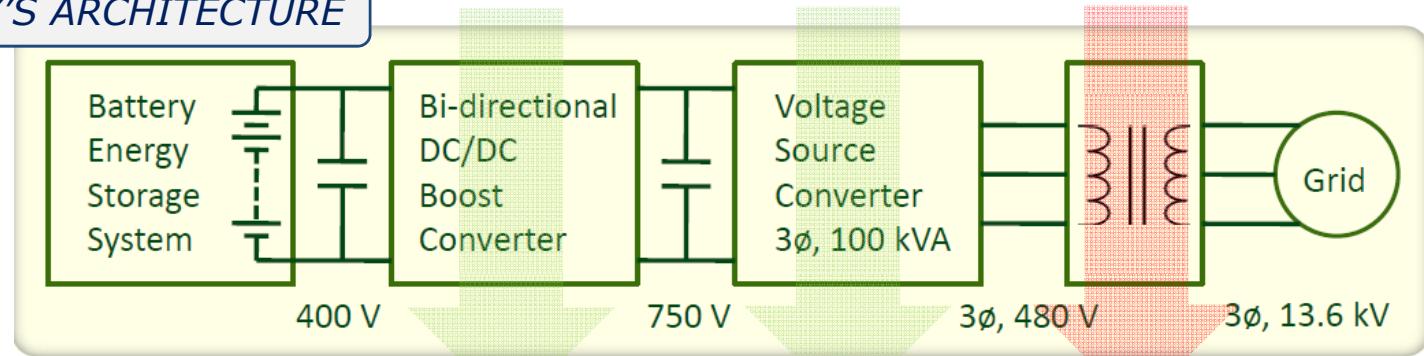


Battery-Based Energy Storage System



Evolving Distribution System Architecture

TODAY'S ARCHITECTURE



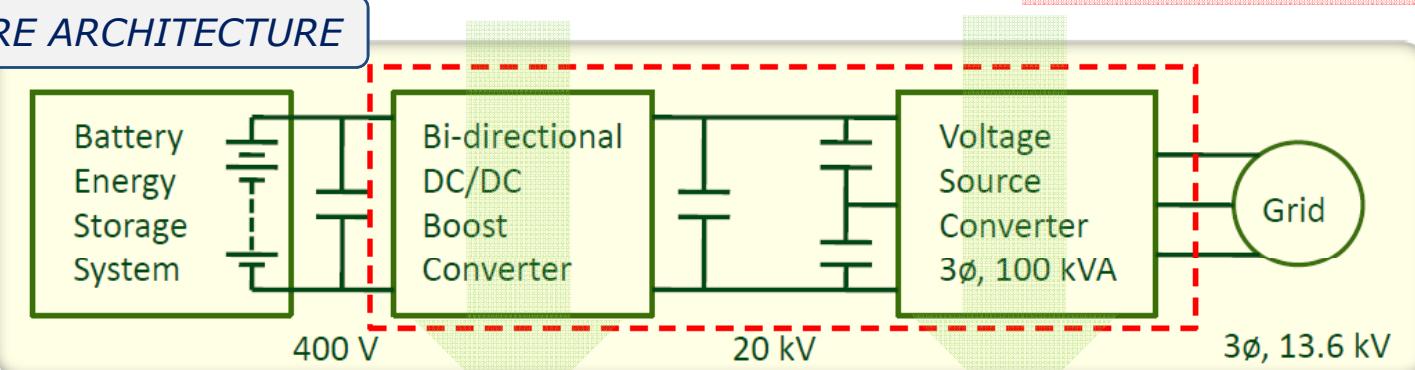
Inverter/Charger

- Silicon IGBT/MOSFET ($\leq 1200V$)

Distribution Transformer

- Conventional

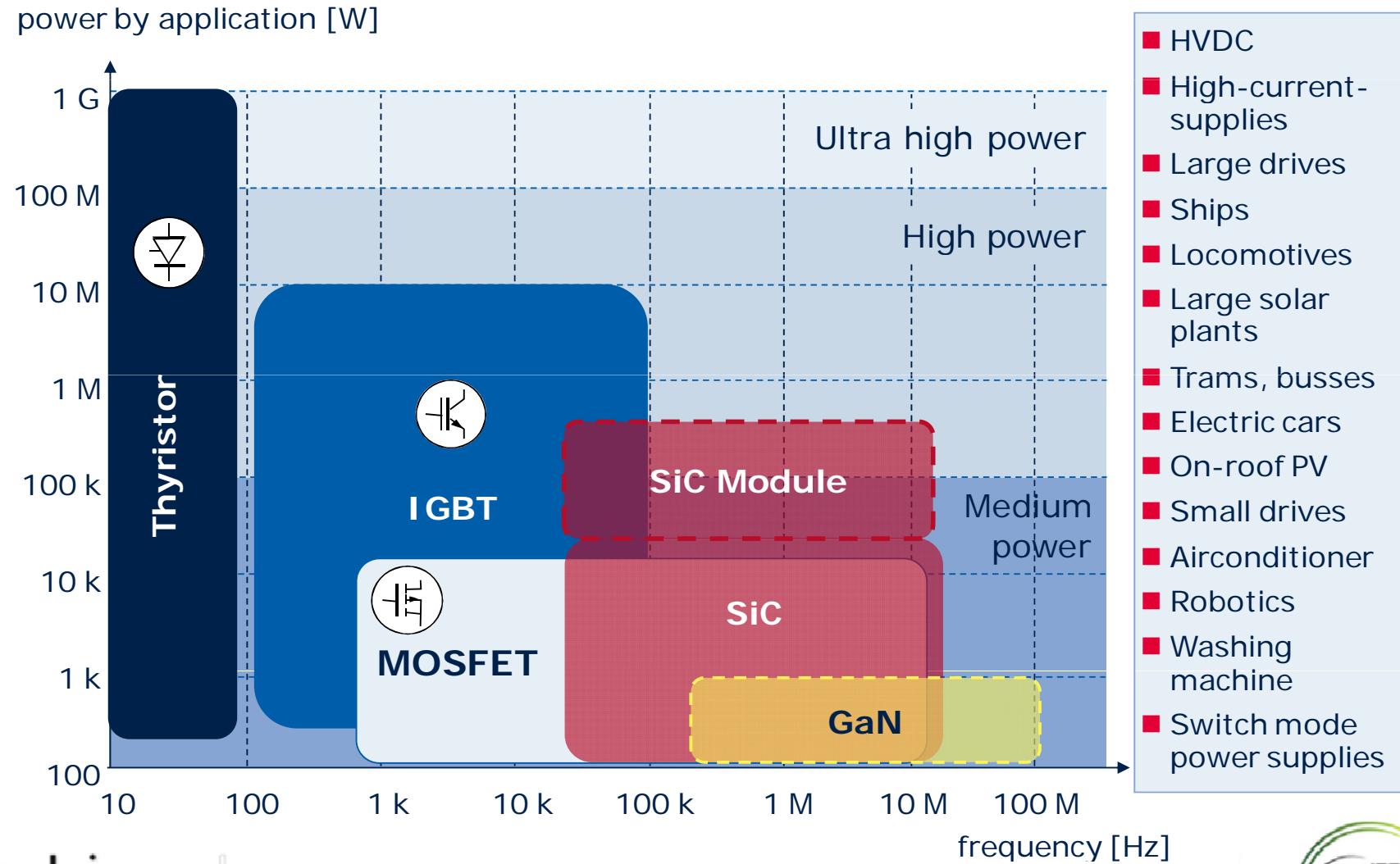
FUTURE ARCHITECTURE



Inverter/Charger/Distribution Transformer
•Cascaded Silicon IGBTs or SiC IGBT ($\geq 15kV$)

Source: "Grid-Scale Energy Storage", ARPA-E Grid-Scale Energy Storage Workshop Summary, 03/2010

Overview of Power Semiconductor Technologies



Semiconductor Smart Grid Requirements



Wafer & Packaging

- Increasing wafer size (4" → 5" → 6" → 8" → 12")
- Decreasing wafer thickness
- New packaging technologies



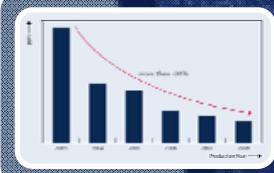
Integration

- Power management
- Sense & control
- Computing



Robustness

- Extended temperature range
- Robust design



Quality & Sustainability

- Zero-defect culture
- Sustainable quality improvement
- Green mindset throughout value chain



Lifetime

- Support of long industry life cycles

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